Erratum to: Thermal Fatigue Evaluation of Pb-Free Solder Joints: Results, Lessons Learned, and Future Trends

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Due to an editing mistake, the content of Table II was erroneously replaced. Table II should read:

Table II. Temperature cycling profiles used in the experimental program

Minimum temp. (°C)	Maximum temp. (°C)	Temp. range (°C)	Dwell time (min)
0	100	100	10
0	100	100	60
−40	100	140	10
−40	100	140	60
25	125	100	10
25	125	100	60
−15	125	140	10
−15	125	140	60
−40	125	165	10